


<div> Telink</div>				Telink Semiconductor (Shanghai) CO., LTD Phone: +8621 2028 1118 Fax: 8621 5038 8081 1500 Zuchongzhi Road Bldg 3 PuDong District, Shanghai, China 201203									
Composition Table													
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.											
From:		HuaTian Technology (Xi An) Co.,Ltd											
Product Name:		TLSR8355F512ET32											
Weight(Unit):		64.1000 mg						Date:	2023/10/17				
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)				
Die1	Telink Die	SMIC BJ	3.3540	Silicon	7440-21-3	3.3540	100.00%	5.23%	1000000				
Die2	GD Die	SMIC BJ	0.2760	Silicon	7440-21-3	0.2760	100.00%	0.43%	1000000				
Lead Frame	A194	AAMI	20.0200	Cu	7440-50-8	19.3193	96.50%	52.45%	965000				
				Fe	7439-89-6	0.4605	2.30%	0.72%	23000				
				P	7723-14-0	0.0300	0.15%	0.05%	1500				
				Zn	7440-66-6	0.0400	0.20%	0.06%	2000				
				Pb	7439-92-1	0.0010	0.01%	0.00%	50				
				Ag	7440-22-4	0.1692	0.85%	0.26%	8450				
				DAF	ATB-120U	Henkel	1.3800	Modified Epoxy Resin	Proprietary	0.9108	66.0%	0.06%	660000
Phenol, polymer with													
3a,4,7,7a-tetrahydro-4,7-methano-1H-indene, glycidyl ether	119345-05-0	0.3174	23.0%					0.50%	230000				
Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	9003-36-5	0.0690	5.0%					0.11%	50000				
Aromatic polyamine	Proprietary	0.0690	5.0%					0.11%	50000				
Epoxy Resin	Proprietary	0.0138	1.0%					0.02%	10000				
Epoxy	L1-403NCA	LEGEND	1.4200	Diethylene glycol monoethyl ether acetate	112-15-2	0.1420	10.00%	0.74%	100000				
				Silica	15468-32-3	0.8520	60.00%	1.33%	600000				
				Acylate resin	Proprietary	0.2130	15.00%	0.33%	150000				
				Epoxy resin	Proprietary	0.1988	14.00%	0.31%	140000				
				Peroxide	Proprietary	0.0142	1.00%	0.02%	10000				
				Wire	HS-ES5	乐金	3.0000	Silver:Wire	7440-22-4	2.8497	94.9900%	0.43%	949900
Gold	7440-57-5	0.0150	0.5000%					0.02%	5000				
Palladium	7440-05-3	0.1350	4.5000%					0.21%	45000				
Platinum	7440-6-4	0.0003	0.0100%					0.00%	100				
Mold Compound	CEL-9240HF	RESONAC Materials	32.0500					Epoxy Resin 1	Trade secret	0.1603	0.50%	43%	5000
				Epoxy Resin 2	Trade secret	0.1603	0.50%	0.25%	5000				
				Epoxy Resin 3	Trade secret	0.1603	0.50%	0.25%	5000				
				Hardener	Trade secret	0.6410	2.00%	1.00%	20000				
				Catalyst	Trade secret	0.0032	0.01%	0.01%	100				
				Carbon black	1333-86-4	0.0641	0.20%	0.10%	2000				
				Amorphous silica1	60676-86-0	28.4572	88.79%	44.40%	887900				
				Amorphous silica2	7631-86-9	2.4038	7.50%	3.75%	75000				
				Plating	TIN	AISEN	2.6000	Tin	7440-31-5	2.5997	99.99%	2.07%	999900
								Others	Trade Secret	0.0003	0.01%	0.00%	100
Total			64.1000			64.1000	100%	1000000					